

## List of Publications by Year in descending order

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#	Article	IF	CITATIONS
1	Measurement and analysis of thermal stresses in 3D integrated structures containing through-silicon-vias. Microelectronics Reliability, 2013, 53, 53-62.	1.7	96
2	Micro-Raman spectroscopy and analysis of near-surface stresses in silicon around through-silicon vias for three-dimensional interconnects. Journal of Applied Physics, 2012, 111, .	2.5	94
3	Thermomechanical characterization and modeling for TSV structures. , 2014, , .		2